

# MECHANICAL CASE OUTLINE

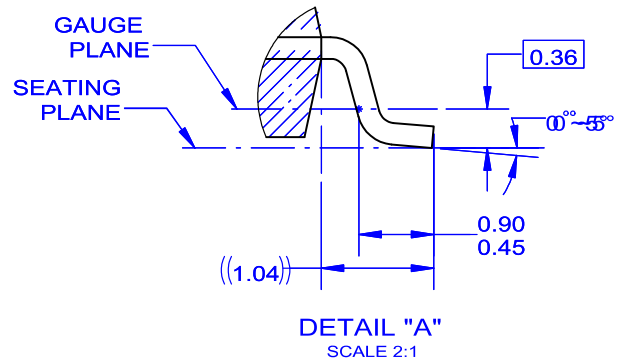
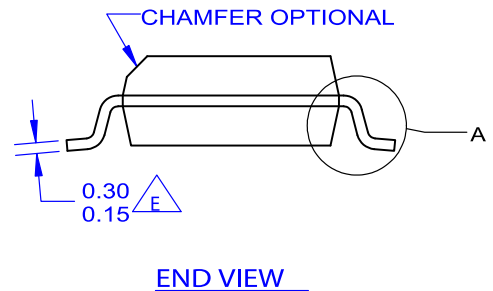
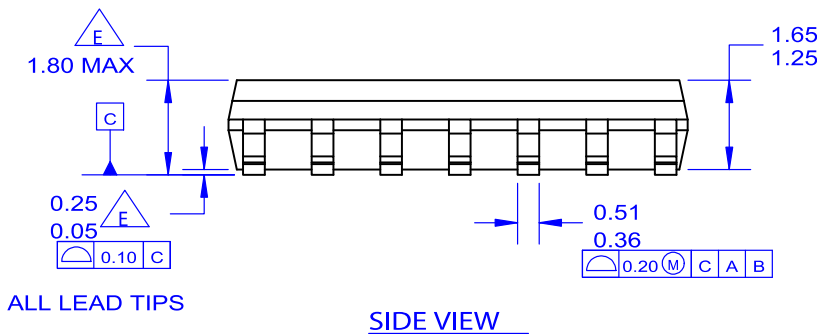
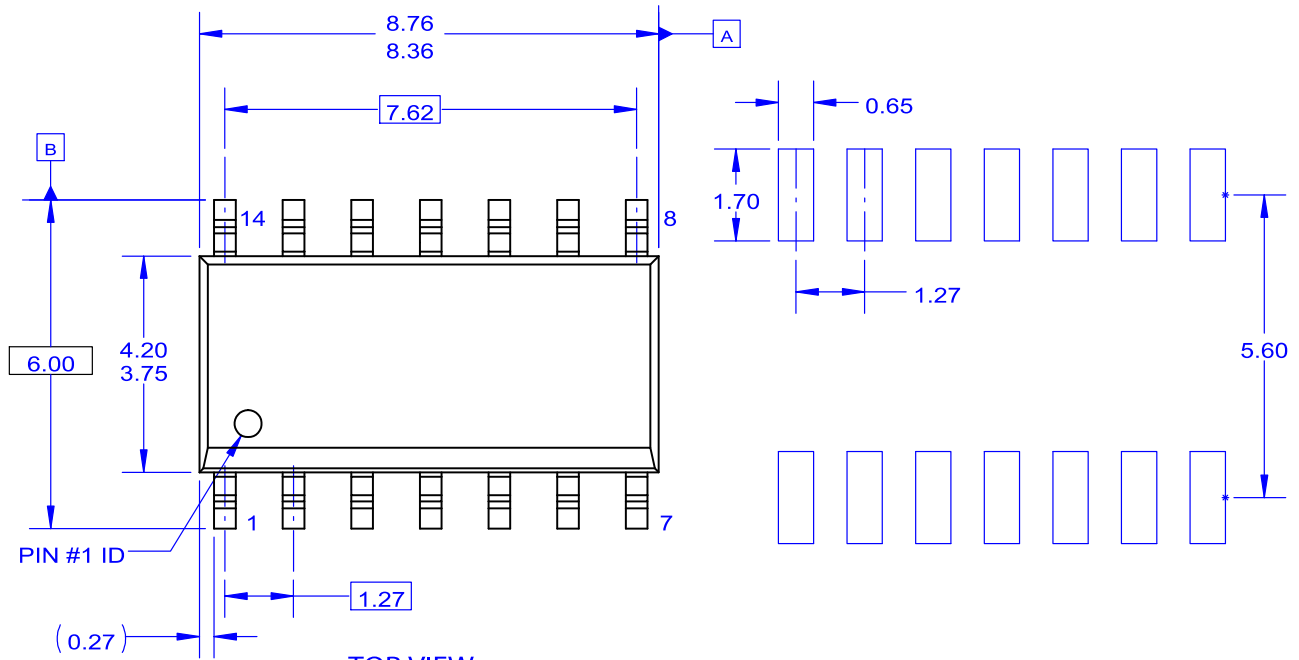
## PACKAGE DIMENSIONS

ON Semiconductor®



SOIC14 N  
CASE 751ER  
ISSUE O

DATE 31 DEC 2016



NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE REFERENCE TO JEDEC MS-012 VARIATION AB.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- E. OUT OF JEDEC STANDARD VALUE.

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